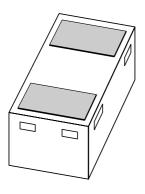
DISCRETE SEMICONDUCTORS

DATA SHEET



1PS10SB63Schottky barrier diode

Product specification

2003 Aug 20





Schottky barrier diode

1PS10SB63

FEATURES

- · Very low diode capacitance
- · Low forward voltage
- Leadless ultra small plastic package (1.0 mm × 0.6 mm × 0.5 mm)
- Boardspace 1.17 mm² (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

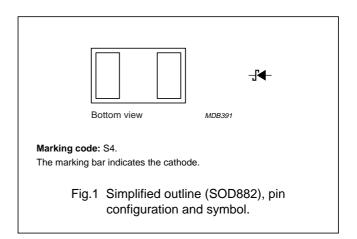
APPLICATIONS

- Ultra high-speed switching
- High frequency detection
- · Zero bias detection
- Mobile communication, digital (still) cameras, PDA's and PCMCIA cards.

DESCRIPTION

An epitaxial Schottky barrier diode encapsulated in a SOD882 leadless ultra small plastic package.

ESD sensitive device, observe handling precautions.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	5	٧
I _F	continuous forward current		_	20	mA
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ ms; } \delta = 0.25$	_	400	mA
I _{FSM}	non-repetitive peak forward current	t _p = 8.3 ms half sinewave; JEDEC method	_	550	mA
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

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Schottky barrier diode

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ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	see Fig.2			
		I _F = 0.1 mA	160	200	mV
		I _F = 1 mA	240	300	mV
I _R	continuous reverse current	see Fig.3			
		V _R = 1 V	0.4	1	μΑ
		V _R = 5 V; note 1	_	50	μΑ
C _d	diode capacitance	V _R = 0 V; f = 1 MHz; see Fig.4	0.35	0.5	pF
L _S	series inductance		0.6	_	nH

Note

1. Pulse test: pulse width = 300 μ s; δ = 0.02.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 with 60 μ m copper strip line.

Soldering

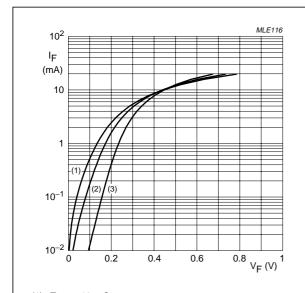
Reflow soldering is the only recommended soldering method.

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Schottky barrier diode

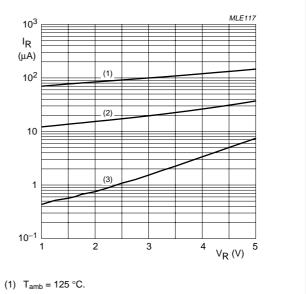
1PS10SB63

GRAPHICAL DATA



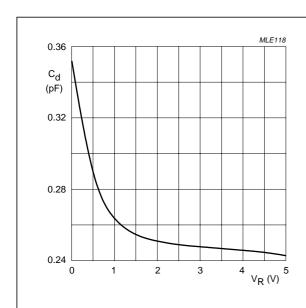
- (1) $T_{amb} = 125 \, ^{\circ}C$.
- (2) $T_{amb} = 85 \, ^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.2 Forward current as a function of forward voltage; typical values.



- (2) $T_{amb} = 85 \, ^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.3 Reverse current as a function of reverse voltage; typical values.



 $f = 1 \text{ MHz}; T_{amb} = 25 \,^{\circ}\text{C}.$

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

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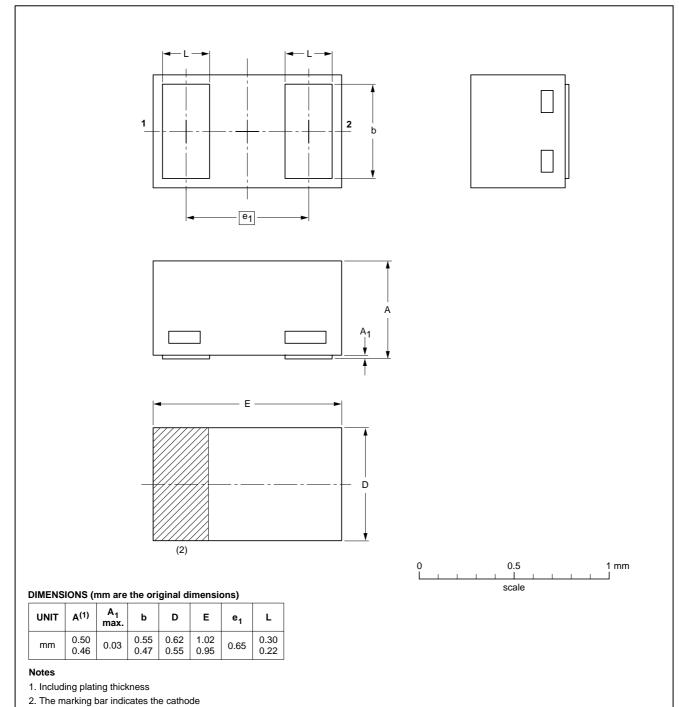
Schottky barrier diode

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PACKAGE OUTLINE

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882



REFERENCES

JEITA

JEDEC

EUROPEAN

PROJECTION

ISSUE DATE

03-04-16 03-04-17

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IEC

OUTLINE

VERSION

SOD882

Philips Semiconductors Product specification

Schottky barrier diode

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Printed in The Netherlands

613514/01/pp7

Date of release: 2003 Aug 20

Document order number: 9397 750 11308

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